# A new 130 nm FE readout chip for microstrip tracking detectors



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LCWS'08, Chicago, Nov 16-20

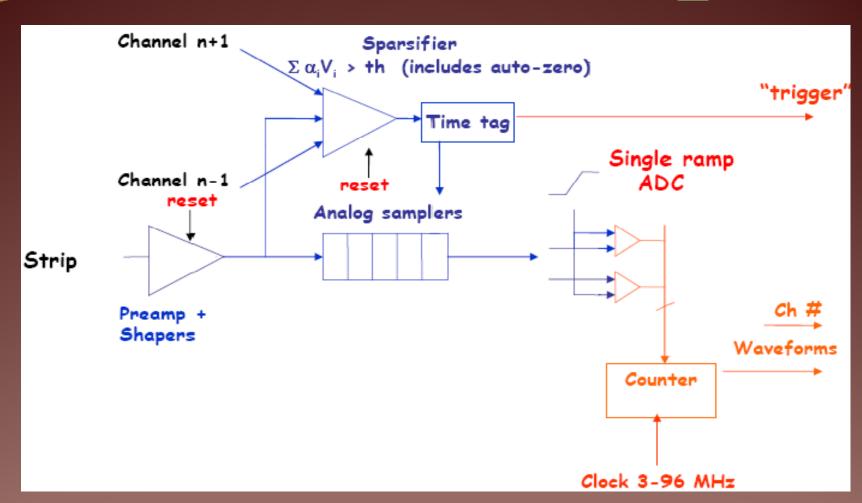
# Synopsis

- Results from SiTR\_130-4
- Design and foundry of the new SiTR\_130-88
  - Perspectives

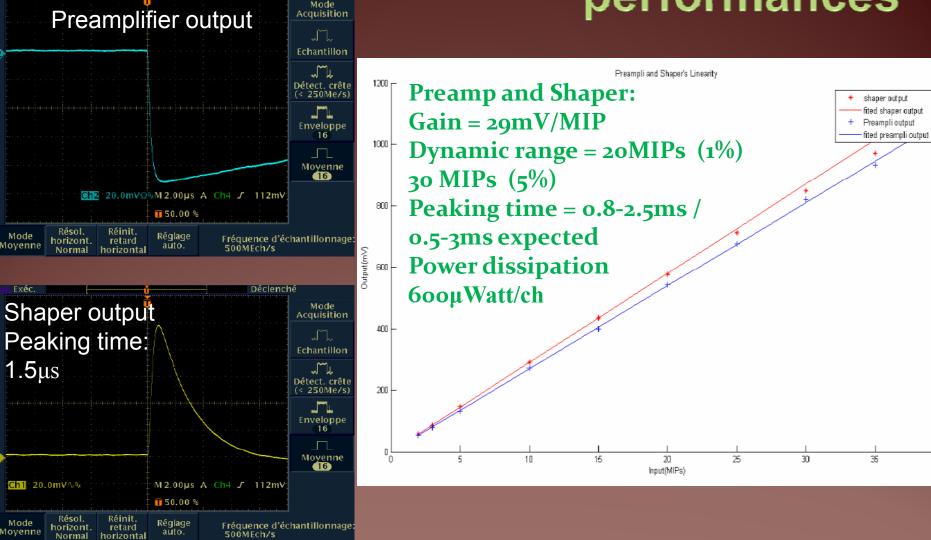
# Results from SiTR\_130-4

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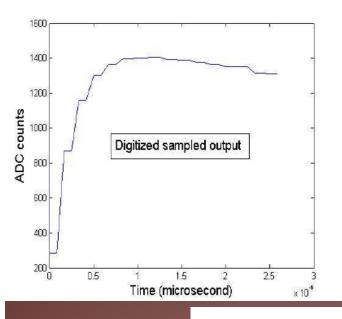
## SiTR\_130-4



# SiTR\_130-4: Preamplifier output Preamplifier output Preamplifier output Preamplifier output Preamplifier output Preamplifier output Preamplifier output

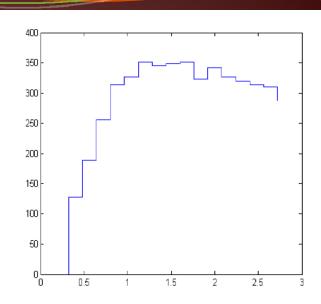


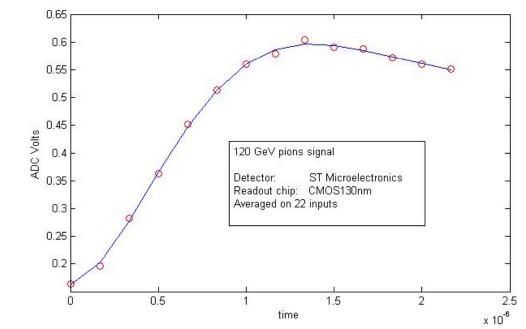
### SiTR\_130-4: performances (cont'd)



Digitized analogue pipeline output test pulse (left) and Laser response of detector + 130nm chip (right)

Digital oscilloscopy



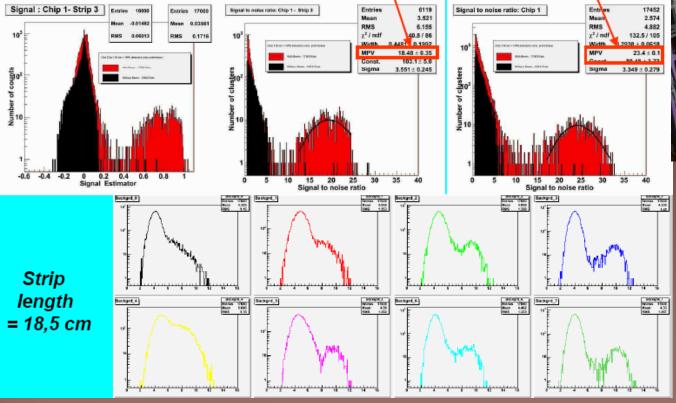


## SiTR 130-4: test-beam performances



#### Results with the new HPK + SiTR-130

Black=beam off, red=beam on; 1 strip S/N 18 1 chip: S/N 23



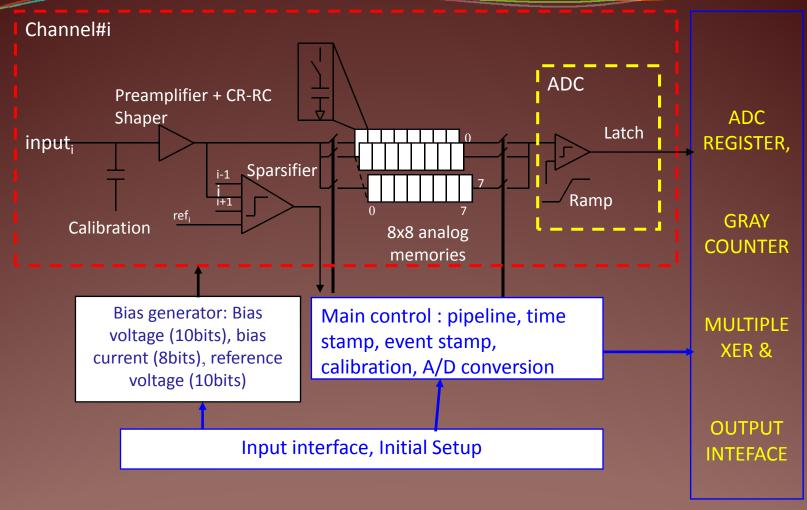


Test beam at SPS
CERN, Oct 2007
combined with EUDET
MAPS telescope

Also extensive studies with Sr90 source at Lab test bench
The beam test includes a collaborative effort with several SiLC institutions
(CU Prague, IFCA, IEKP, HEPHY, LPNHE, OSU, Torino U./INFN, CERN and
DESY collaboration as well)

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## SiTR\_130-88 schema



After very encouraging results obtained with the first pre-prototype Go to the full version: SiTR\_130-88

FE Readout Electronics for Strip tracking, A. Savoy-Navarro

#### Main features of new-circuit

88 channels (1 test channel): Preamplifier, shaper, sparsifier, analogue pipeline (8x8 cells), 12 bits ADC

2D memory structure: 8x8/channels

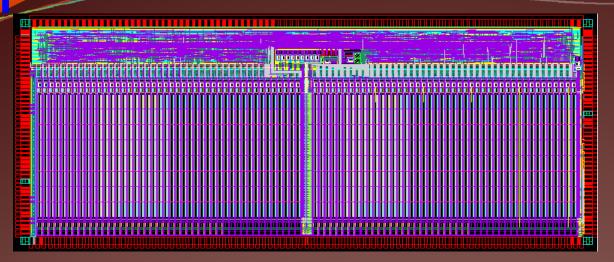
#### Fully digital control:

- Bias voltage(10 bits) and current (8 bits)
- Power cycling (can be switched on and off)
- Shaping time programmable
- Sampling frequency programmable
- Internal calibration (fully programmable 10 bits DAC)
- Sparsifier's threshold programmable per channel
- Event tag and time tag generation
- => High fault tolerance
- => High flexibility, robustness

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2 Trigger modes: Internal (Sparsification integrated)
External (LVTTL) for beam test

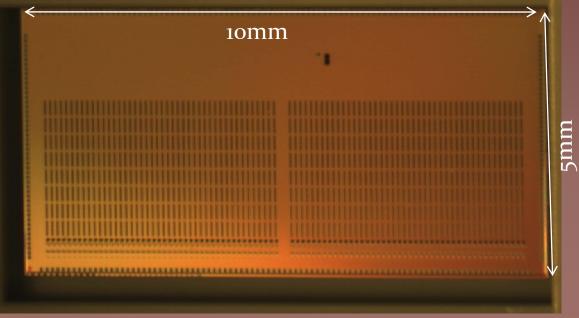
#### LAYOUT VIEW and PHOTOGRAPH



Size: 5mmx10mm 88 channels (105um pitch) 105umx3.5mm/channel

Analog: 9.5mmx3.5mm Digital: 9.5mmx700um

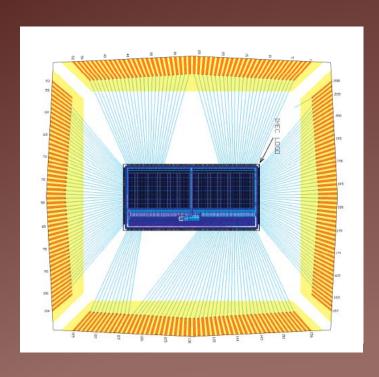
#### Submitted June 24th '08, received September 12 the naked chips



Photograph of the new chip SiTR\_130-88

#### New readout chip in 0.13 µm: packaged version

#### **BONDING DIAGRAM FOR CQFP208 PACKAGE**



Package 208 pins

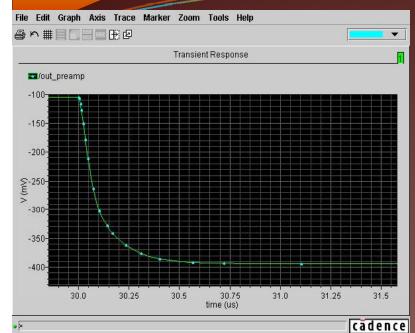
- 50 analog input
- 21 analog test out
- 33 digital pin (22 test pins)
- 107 supply pins

20 packaged chips delivered October 15th

For a a detailed test of chip functionality & performances

Test is "easy" because the chip is "fully programmable"

### Summary of simulation studies



Main present results from the simualtion studies Preamplifier:

Charge gain: 27mV/MIP 5%

Linearity: 17 MIP (1%) to 29 MIP (5%)

Shaper: 30mV/MIP ± 5% Shaping time: 0.5 to 1.5 μs Linearity: idem premaplifier Noise: 625 + 9 e-/pF (1.5 μs)

Pipeline (8x8)

Sampling rate (2)

Linearity: idem premaplifier

ADC conversion time: about 85 μs (48 MHhz clock)

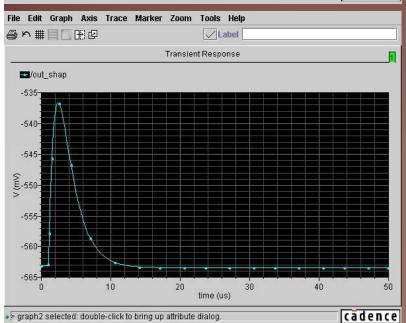
Calibration:

Integrated capacitor: 100 fF

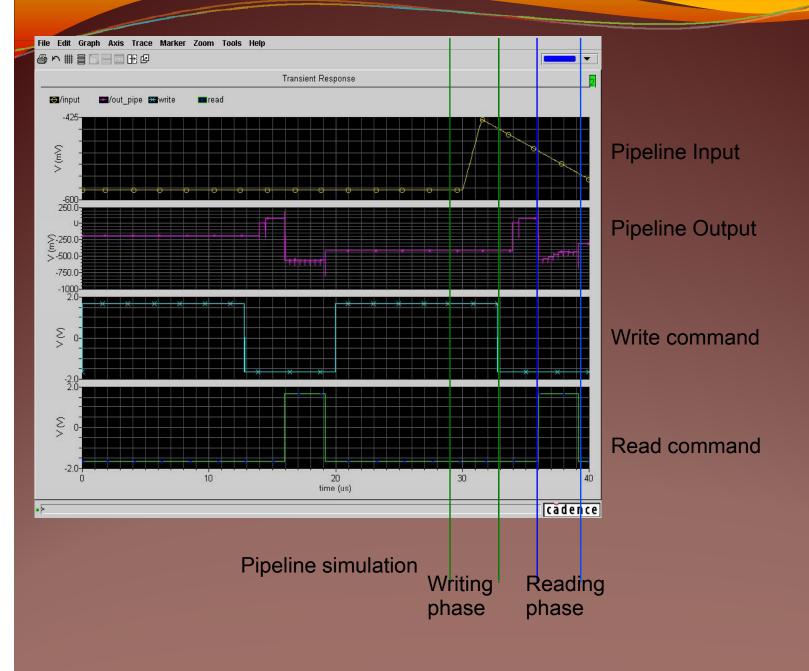
Calibration pulse amplitude: 10 bits DAC (same as bias

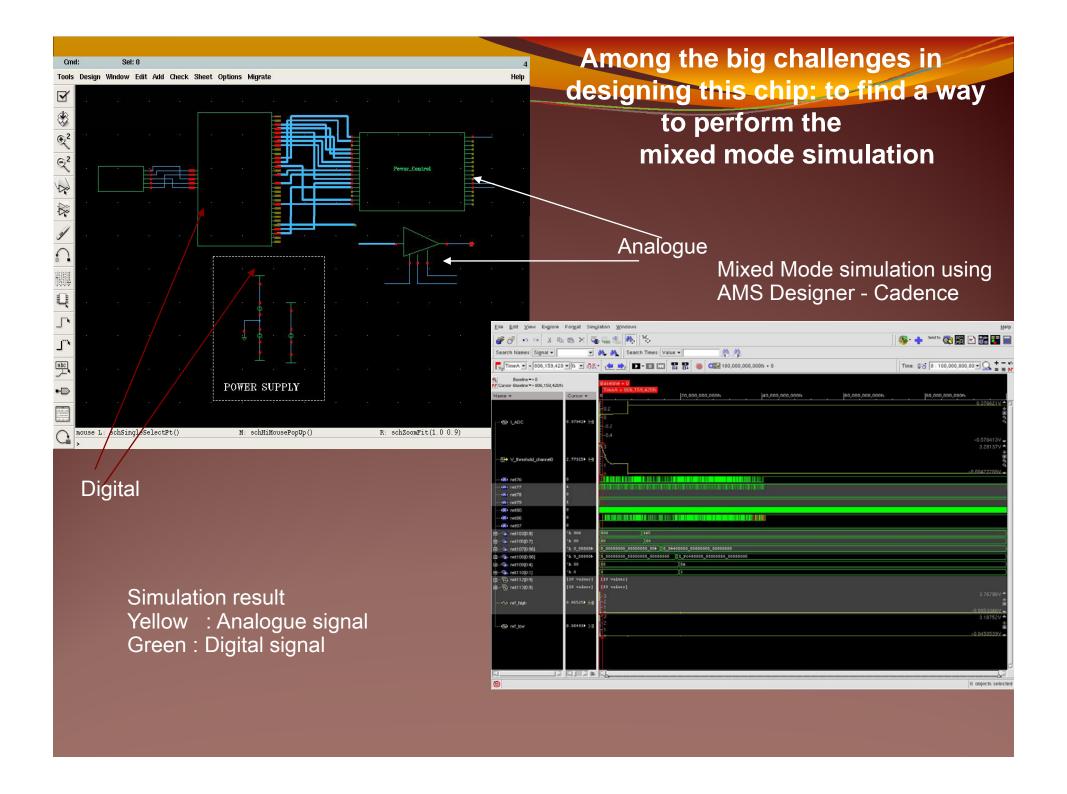
generator)

Overall power dissipation per channel: about 1mWatt Total, not including power cycling

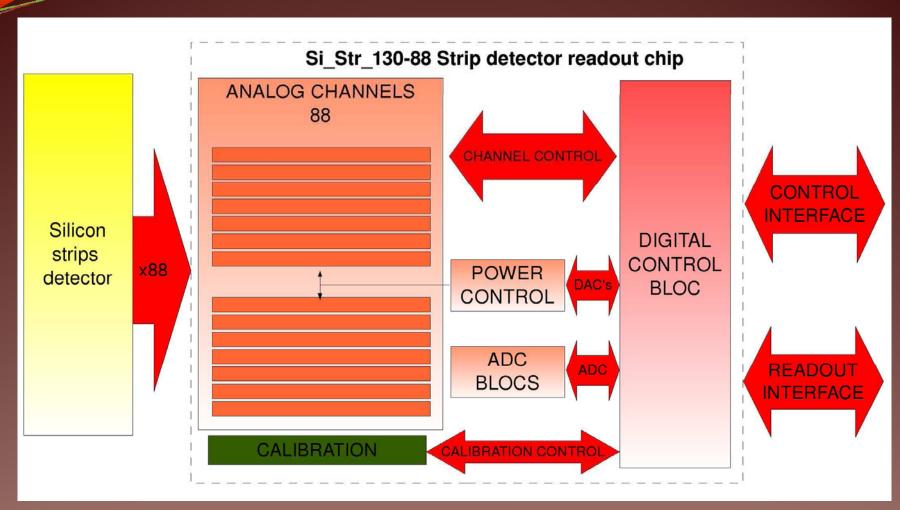


## Summary of simulation studies (con'td)



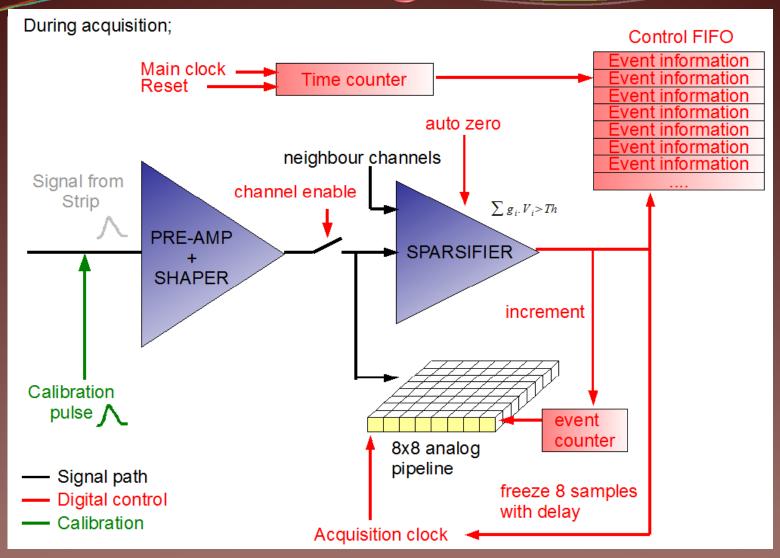


# Digital part



SiTR\_130-88: System overview

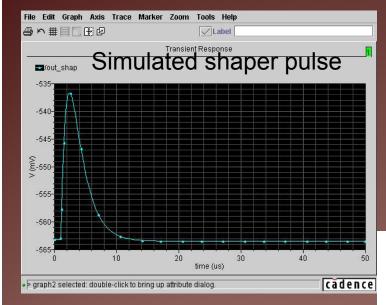
# DAQ-during the bunch-train



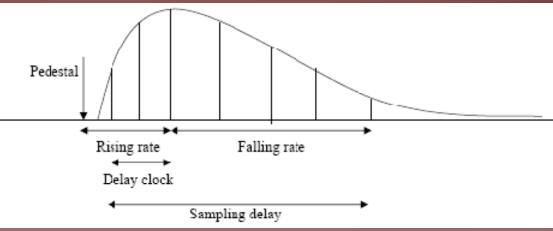
#### Sampling and conversion time:

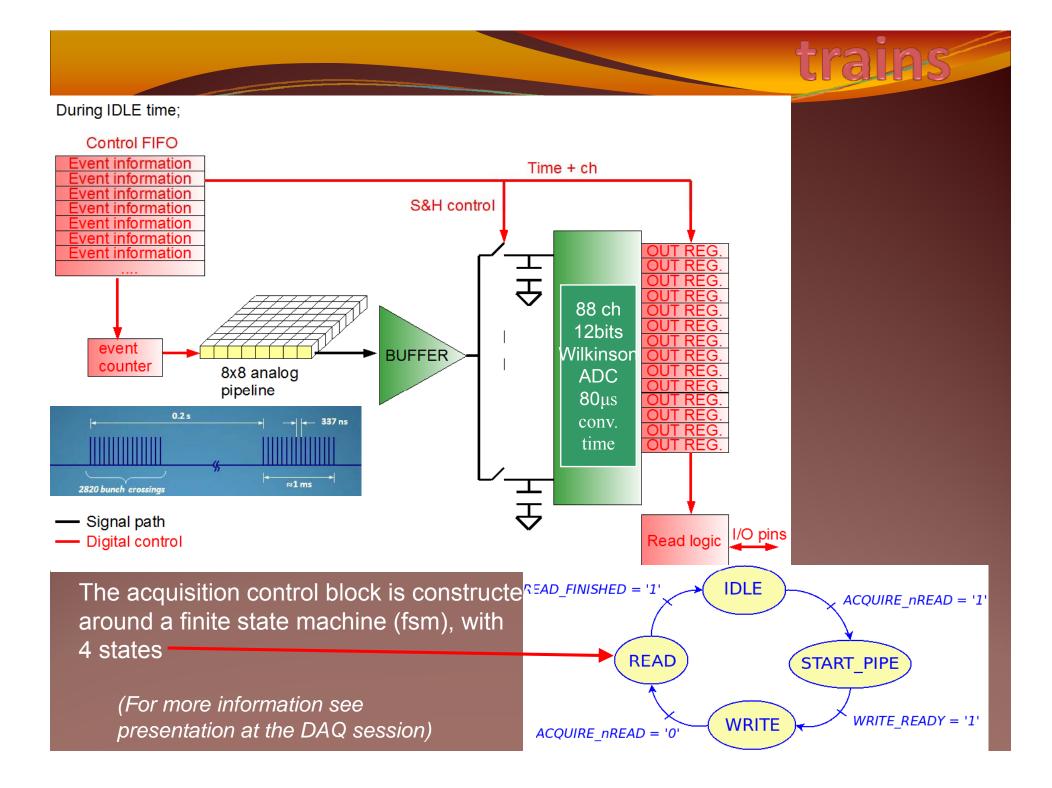
All the 88 channels of the chip are converted in parallel.

There are 8x8 samples to be converted per channel; the conversion time per channel Is approximately 85 µs thus a total of 5.44 ms is needed for the conversion



# Reconstruction of the pulse height: 8 samples including pedestal





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## Next version improvements

- Go to basic blocks of 256 channels and build modules of 512 channels or 1024 out of them (multiplexing factor is still under investigation)
- Thinning of the chip
- Next version in full wafer process (gain in space)
- Include latest results from the tests on the present chip
- Try the 90 nm CMOS technology
- For the longer term it is intended to prepare a fast version CLIC-like
- Pursue the direct connection chip onto the strip detector (bump bonding now, and starting to investigate 3D vertical interconnect as part of the global effort)

NOW WE ARE WORKING ON TESTING THIS CHIP!!